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Kitamura et al.(10) **Pub. No.: US 2022/0369512 A1**(43) **Pub. Date: Nov. 17, 2022**(54) **ELECTRONIC APPARATUS, COOLING
DEVICE, AND METHOD FOR
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(2013.01); **G06F 1/203** (2013.01)(57) **ABSTRACT**

An electronic apparatus includes: a chassis; a heat generating element provided in the chassis; and a cooling device that has a cooling fin, a heat pipe connecting the cooling fin and the heat generating element, and a pressing assembly pressing the heat pipe against the heat generating element, and is provided in the chassis. The heat pipe has: a heat absorbing section that absorbs heat generated by the heat generating element; and a thin plate section having a thickness which is smaller than that of the heat absorbing section. The pressing assembly has: a base assembly relatively fixed to the chassis; and a bridge section that is provided integrally with the base assembly and placed on a surface of the thin plate section in such a manner as to extend over the heat pipe in a width direction.

